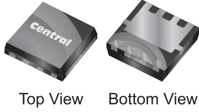
Material Composition Specification

TLM833 Case



Top View Bottom View

Device average mass . . . . 23 mg

Fluctuation margin . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	2.6%	0.6	Si	7440-21-3	2.6%	0.6	26,035
bond wire	gold	1.04%	0.24	Au	7440-57-5	1.04%	0.24	10,414
leadframe	Cu alloy w/ silver plating	33.7%	7.77	Cu	7440-50-8	32.8%	7.56	328,040
				Fe	7439-89-6	0.79%	0.182	7,897
				Zn	7440-66-6	0.04%	0.009	391
				Ag	7440-22-4	0.07%	0.016	694
die attach	silver epoxy	1.04%	0.24	epoxy resin	Proprietary	0.22%	0.05	2,170
				Ag	7440-22-4	0.82%	0.19	8,244
encapsulation*	EMC GREEN	51.2%	11.8	silica (fused)	60676-86-0	43.52%	10.03	435,217
				epoxy resin	Proprietary	3.25%	0.75	32,544
				epoxy, cresol novolac	29690-82-2	1.02%	0.235	10,197
				phenol resin	9003-35-4	3.25%	0.75	32,544
				carbon black	1333-86-4	0.15%	0.034	1,475
plating	matte tin	10.41%	2.4	Sn	7440-31-5	10.41%	2.4	104,140

*EMC GREEN molding compound is Halogen-Free.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R2 (3-June 2011)